



## PATENT ABSTRACTS OF JAPAN

(11) Publication number: **2002062668 A**(43) Date of publication of application: **28.02.02**

(51) Int. Cl.

**G03F 7/42**  
**H01L 23/50**  
**H05K 3/06**

(21) Application number: **2000245486**(22) Date of filing: **14.08.00**(71) Applicant: **MITSUBISHI GAS CHEM CO INC**

(72) Inventor: **ABE HISAOKI**  
**MARUYAMA TAKEHITO**  
**AOYAMA TETSUO**

(54) **METHOD FOR REMOVING PHOTORESIST**

## (57) Abstract:

**PROBLEM TO BE SOLVED:** To provide a method for removing a photoresist by which the remaining photoresist in the photolithographic process of forming a pattern on the metal face of an electronic material such as a lead frame, printed wiring board or the like can be removed in a short time without deforming the

metal pattern.

**SOLUTION:** The removing liquid used in the method consists of an aqueous solution containing a quaternary ammonium hydroxide, water-soluble amines, hydroxyl amines, and if necessary, a corrosion preventive agent for copper-based metals.

**COPYRIGHT:** (C)2002,JPO